SN54F10, SN74F10 TRIPLE 3-INPUT POSITIVE-NAND GATES

SDFS039A - MARCH 1987 - REVISED OCTOBER 1993

Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Standard Plastic and Ceramic 300-mil DIPs

description

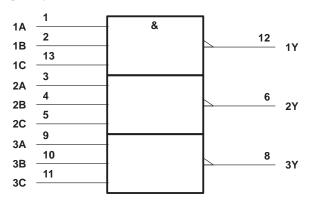
These devices contain three independent 3-input NAND gates. They perform the Boolean functions $Y = \overline{A \bullet B \bullet C}$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

The SN54F10 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F10 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE (each gate)

	INPUTS		OUTPUT
Α	В	С	Y
н	Н	Н	L
L	Х	Х	н
X	L	Х	н
X	Х	L	н

logic symbol[†]

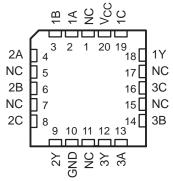


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

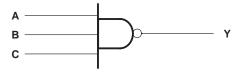
SN54F10 J PACKAGE SN74F10 D OR N PACKAGE (TOP VIEW)									
٦		∇							
1A [1	14	V _{CC}						
1B [2	13] V _{CC}] 1C						
2A [3	12] 1Y						
2B 🛛	4	11] 3C						
2C [5	10] 3B						
2Y [6	9] 3A						
GND [7	8] 3Y						

SN54F10 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

logic diagram, each gate (positive logic)



PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

SN54F10, SN74F10 TRIPLE 3-INPUT POSITIVE-NAND GATES

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1)	
Input current range	
Voltage range applied to any output in the high state	
Current into any output in the low state	40 mA
Operating free-air temperature range: SN54F10	
SN74F10	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

recommended operating conditions

		SN54F10			S	6N74F10		UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IIK	Input clamp current			-18			-18	mA
ЮН	High-level output current			- 1			- 1	mA
IOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		EST CONDITIONS		SN54F10		5	SN74F10		UNIT
PARAMETER	TEST CONDITIONS			TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = -18 mA			-1.2			-1.2	V
VOH	$V_{CC} = 4.5 V,$	I _{OH} = - 1 mA	2.5	3.4		2.5	3.4		V
VОН	V _{CC} = 4.75 V,	I _{OH} = - 1 mA				2.7			v
VOL	V _{CC} = 4.5 V,	I _{OL} = 20 mA		0.3	0.5		0.3	0.5	V
lj	$V_{CC} = 5.5 V,$	$V_{I} = 7 V$			0.1			0.1	mA
IIH	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μΑ
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.5 V			- 0.6			- 0.6	mA
los§	V _{CC} = 5.5 V,	$V_{O} = 0$	-60		-150	-60		-150	mA
Іссн	V _{CC} = 5.5 V,	$V_{I} = 0$		1.4	2.1		1.4	2.1	mA
ICCL	V _{CC} = 5.5 V,	V _I = 4.5 V		5.1	7.7		5.1	7.7	mA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.



SN54F10, SN74F10 TRIPLE 3-INPUT POSITIVE-NAND GATES

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switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 5 V,$ $C_{L} = 50 pF,$ $R_{L} = 500 Ω,$ $T_{A} = 25°C$			$V_{CC} = 4.5 V \text{ to } 5.5 V,$ $C_{L} = 50 \text{ pF},$ $R_{L} = 500 \Omega,$ $T_{A} = \text{MIN to MAX}^{\dagger}$				UNIT
			′ F10			SN54F10 SN74F1			F10	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	A, B, or C	v	1.6	3.3	5	1.2	7	1.6	6	20
^t PHL	A, B, 01 C	Ť	1	2.8	4.3	1	6.5	1	5.3	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and waveforms are shown in Section 1.





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-9757901Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	· · · ·
5962-9757901QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
5962-9757901QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Call TI	
JM38510/33003B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
JM38510/33003BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
JM38510/33003BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
M38510/33003B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
M38510/33003BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
M38510/33003BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	
SN54F10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74F10D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74F10N3	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI	
SN74F10NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74F10NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74F10NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54F10FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	



Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SNJ54F10J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54F10W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54F10, SN74F10 :

• Catalog: SN74F10

Military: SN54F10

NOTE: Qualified Version Definitions:

PACKAGE OPTION ADDENDUM



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25-Jan-2012

• Catalog - TI's standard catalog product

• Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*A	I dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74F10DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74F10NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

11-Mar-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F10DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74F10NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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